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XA-9890
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Takashi MIWA et al.

Appln. No.: 10/606,891

Group Art Unit: 2824

Filed: June 27, 2003

Examiner: A. Tran

For: STACKED LARGE-SCALE INTEGRATED CIRCUIT (LSI)
SEMICONDUCTOR DEVICE WITH MINIATURIZATION AND THINNING OF
PACKAGE (AS AMENDED)

* * *

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Notice mailed August 16, 2005, the Notice is improper and should be withdrawn. As stated on page 10 of the Amendment filed August 8, 2005, the earlier marked up version of the specification (see attached copy of postcard receipt) still applies.

The Commissioner is hereby authorized to charge to Deposit Account No. 50-1165 any fees under 37 C.F.R. §§ 1.16 and 1.17 that may be required by this paper and to credit any overpayment to that Account. If any extension of time is required in connection with the filing of this paper and

has not been requested separately, such extension is hereby requested.

Respectfully submitted,

NHS:dmt

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By: Nelson H. Shapiro
Nelson H. Shapiro
Reg. No. 17,095

August 17, 2005



Applicants: Takashi MIWA et al.
Appln. No. 10/606,891
Filed: June 27, 2003

XA-9890

For: STACKED LARGE SCALE INTEGRATED CIRCUIT (LST)
SEMICONDCUTOR DEVICE WITH MINIATURIZATIN AND THINNING OF
PACKAGE (as amended)

Attached: Amendment, 2 sheets of drawings, Petition for Ext. of Time
Marked-up copy of specification, clean version of spec.

RECEIVED IN THE U.S. PATENT AND TRADEMARK OFFICE ON:

